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Investigation on Thermal Resistance of a Novel Evaporator Wick Structure

Wang-yu Liu, Yuan-qiang Luo, Wei Chen, Yi Peng

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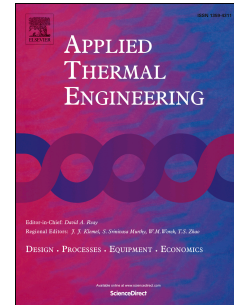
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**Highlights**

- (1) A novel evaporator wick structure was fabricated through chemical etching.
- (2) A mathematical model of the two parts of thermal resistance was developed.
- (3) An experiment was set up to simulate the working conditions of an evaporator.

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